

Enhancing the Performance of Hybrid Pixel Detectors for High-Energy Transmission Electron Microscopy by Using High-Z Sensors

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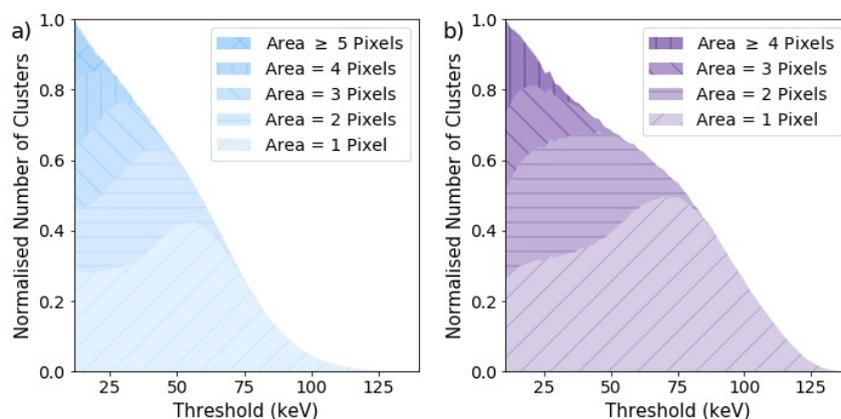
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Hybrid pixel detectors (HPDs) are a class of direct electron detector (DED) that have been used to achieve novel insights in both biology [1] and materials science [2]. They consist of an application specific integrated circuit (ASIC) bonded to a thick ($\geq 300\mu\text{m}$) sensor that protects the ASIC from incident electrons, making them highly robust. Their sophisticated on-pixel signal processing circuitry makes them capable of noiseless operation and high frame rates. These properties are highly advantageous for many applications in transmission electron microscopy, including diffraction-based experimental modalities [1, 2] and high-speed filming of dynamical processes [3].

Although HPDs can perform as ideal detectors when using low-energy ($\leq 120\text{keV}$) electrons, their performance deteriorates as the energy, and therefore range, of incident electrons increases. However, the range of an incident electron decreases as the atomic number, Z , of the sensor increases [4]. HPD sensors are usually made from Si ($Z=14$), but, unlike the sensors of other DEDs, can be made from high- Z materials such as GaAs:Cr (average $Z=32$). Using high- Z sensors should therefore improve the performance of HPDs, but there has been speculation that any improvement in performance may be mitigated by a reduction in detector efficiency due to the increased backscatter of incident electrons [5].

We have compared the performance of two Medipix3 HPDs [6], one with a Si sensor and one with a GaAs:Cr sensor, using electrons in the energy range of 60keV-300keV. The Medipix3 counts electrons on-pixel, with a pixel registering an incident electron as a hit if the signal induced on the pixel exceeds a user-set threshold. Measurements of the devices' modulation transfer function and detective quantum efficiency as a function of counting threshold confirm that the GaAs:Cr device out-performs the Si device when using high-energy electrons and can match and surpass the performance of an ideal detector in some respects. Analysis of the detectors' response to individual electrons such as that seen in figure 1 provides further insight into detector response. Our results confirm that high- Z sensors can enhance the performance of HPDs used in transmission electron microscopy, increasing the range of experiments for which they are suitable, and have important implications both for how high- Z sensors can be best utilised in electron microscopy and for the development of future DEDs.

Figure 1: Number of pixel clusters due to individual 200keV electrons as a function of counting threshold, normalised to the maximum number of clusters recorded, for a) the Si device and b) the GaAs:Cr device. The shading indicates how the number of pixel clusters of a given area changes with counting threshold. The typical cluster size is much smaller for the GaAs:Cr device than it is for the Si device at low threshold, indicating that the GaAs:Cr device has a superior point spread function. The number of clusters falls to zero at a counting threshold equal to the maximum amount of energy deposited on a single pixel.



References

- [1] R. Bücken et al., *Nat. Commun.*, 11, 996, (2020)
- [2] S. Fang et al., *Nat. Commun.*, 210, 1127, (2020)
- [3] G. W. Paterson et al., *Ultramicroscopy*, 210, (2020)
- [4] G. McMullan et al., *Ultramicroscopy*, 107, (2007)
- [5] G. McMullan et al., *Ultramicroscopy*, 109, (2009)
- [6] R. Ballabriga et al., *Nucl. Instruments Methods Phys. Res. Sect. A Accel. Spectrometers, Detect. Assoc. Equip.*, 633, (2011)